

More information on AI Technology, Inc.'s Die Attach Paste Adhesives:

To achieve the highest level of ease in component soldering operations without pre-baking, AIT die-attach pastes have been engineered with a molecular structure of low moisture absorption. This low moisture absorption is reflected in the consistent bond strength under extreme moisture exposure.

With the increased usage of lead-free soldering, high temperature stability is critical. Low weight loss is engineered in AIT die-attach paste adhesives using a stable molecular structure. The following weight loss measure is a good indicator of the ability of AIT die-attach pastes to withstand higher temperature soldering operations and long-term high temperature applications.

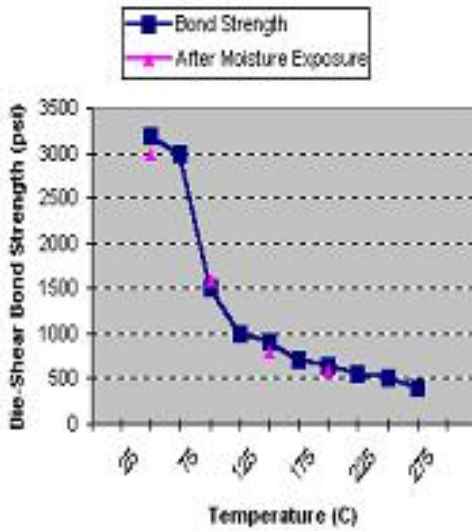
To enhance the productivity of die-attach operations, AIT die-attach pastes for high volume applications have been designed with 100% solids without diluent or solvent. The use of fast curing agents enables the adhesive to cure rapidly. AIT die-attach pastes are ideal for in-line curing manufacturing without additional post curing.

AIT also designed a die-attach paste with long pot-life for high volume applications to ensure success in manufacturing operations.

For more information, recommendations and assistance, please contact AIT sales and engineering:AIT technical sales and service department can also be reached at: 1-609-799-9388 or 1-800-735-5040 (EST) and Fax: 609-799-9308

Bond Strength Moisture Sensitivity

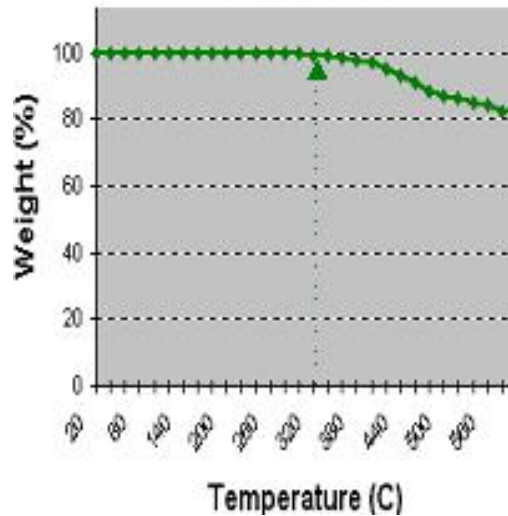
(After 85°C,85%RH @ 168hr)



Molecular Stability

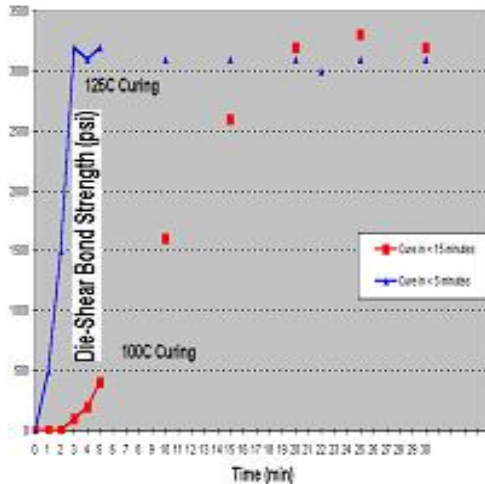
(Die-Attach Paste)

(TGA @ 10°C/min)



Rapid Curing Die-Attach Pastes

- ME8630-RC
- ME8650-RC
- @100-150°C



Long Pot-Life Pastes

- ME 8630-RC
- ME 8650-RC
- Engineered for Productivity

